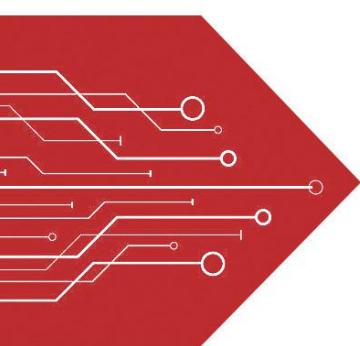


# MSKSEMI

SEMICONDUCTOR



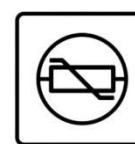
ESD



TVS



TSS



MOV



GDT



PLED

Product data sheet

**VOLTAGE RANGE**

20 to 100 Volts

**CURRENT**

2.0 Ampere



SMB

**FEATURES**

- \* Ideal for surface mount applications
- \* Easy pick and place
- \* Built-in strain relief
- \* Low forward voltage drop

**MECHANICAL DATA**

- \* Case: Molded plastic
- \* Epoxy: UL 94V-0 rate flame retardant
- \* Metallurgically bonded construction
- \* Polarity: Color band denotes cathode end
- \* Mounting position: Any
- \* Weight: 0.093 grams

**MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS**

Rating 25°C ambient temperature unless otherwise specified.

Single phase half wave, 60Hz, resistive or inductive load.

For capacitive load, derate current by 20%.

P/N(MARK)	SS22B	SS23B	SS24B	SS25B	SS26B	SS28B	SS29B	SS210B	UNITS
Maximum Recurrent Peak Reverse Voltage	20	30	40	50	60	80	90	100	V
Maximum RMS Voltage	14	21	28	35	42	56	63	70	V
Maximum DC Blocking Voltage	20	30	40	50	60	80	90	100	V
Maximum Average Forward Rectified Current See Fig. 1						2.0			A
Peak Forward Surge Current, 8.3 ms single half sine-wave superimposed on rated load (JEDEC method)					50				A
Maximum Instantaneous Forward Voltage at 2.0A	0.55		0.70		0.85				V
Maximum DC Reverse Current Ta=25°C		0.1			0.02				mA
at Rated DC Blocking Voltage Ta=100°C		5			2				mA
Typical Junction Capacitance (Note1)		170							pF
Typical Thermal Resistance R <sub>JA</sub> (Note 2)		75							°C/W
Operating Temperature Range T <sub>J</sub>		-65	—	+150					°C
Storage Temperature Range T <sub>STG</sub>		-65	—	+150					°C

**NOTES:**

1. Measured at 1MHz and applied reverse voltage of 4.0V D.C.

2. Thermal Resistance Junction to Ambient.

RATING AND CHARACTERISTIC CURVES (SS22B THRU SS210B)

FIG.1-TYPICAL FORWARD CURRENT DERATING CURVE

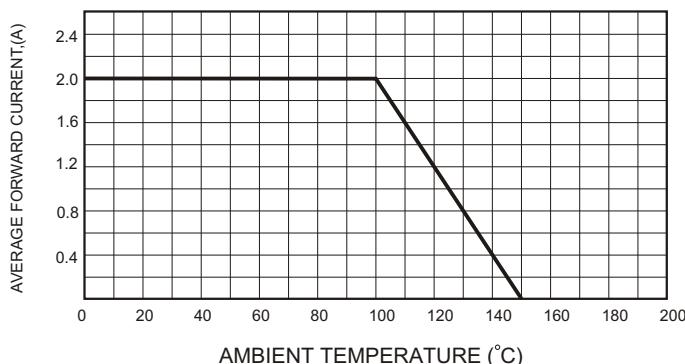


FIG.3-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

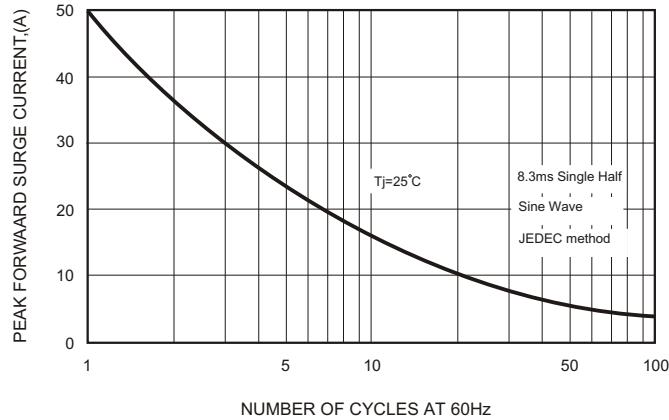


FIG.4-TYPICAL JUNCTION CAPACITANCE

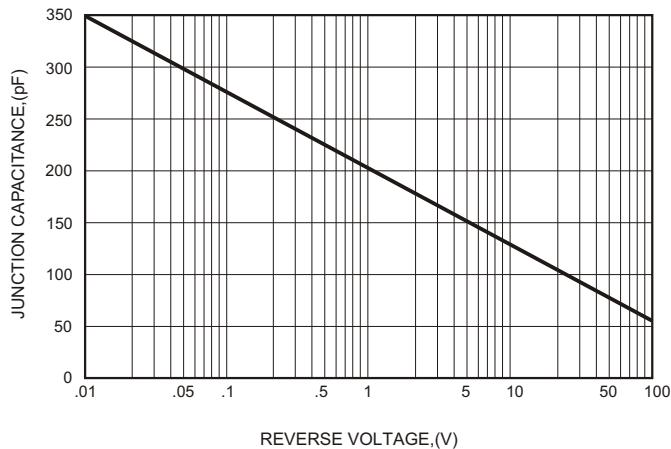


FIG.2-TYPICAL FORWARD CHARACTERISTICS

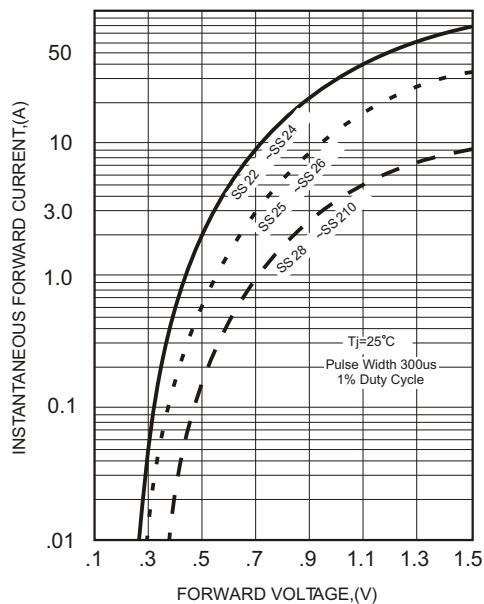
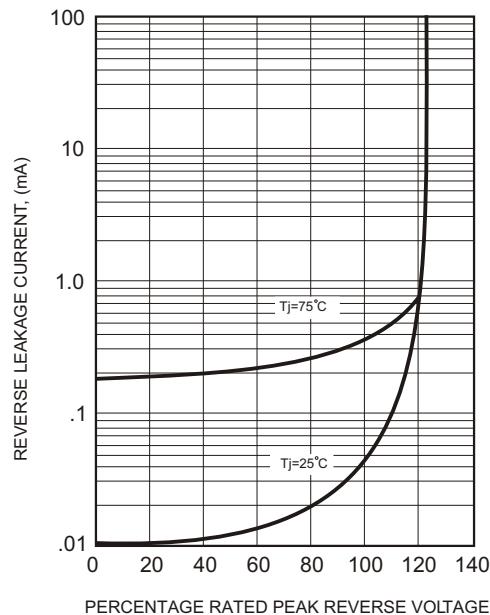
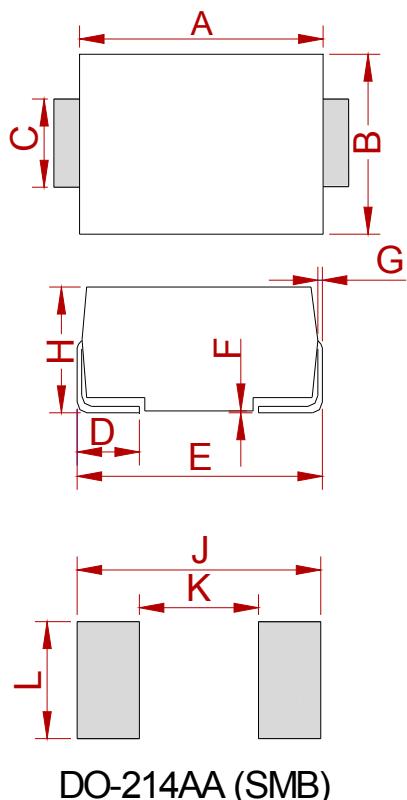


FIG.5 - TYPICAL REVERSE CHARACTERISTICS



**PACKAGE MECHANICAL DATA**


Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.25	4.75	0.167	0.187
B	3.30	3.94	0.130	0.155
C	1.85	2.21	0.073	0.087
D	0.76	1.52	0.030	0.060
E	5.08	5.59	0.200	0.220
F	0.051	0.203	0.002	0.008
G	0.15	0.31	0.006	0.012
H	2.11	2.44	0.083	0.096
J	6.80		0.270	
K		2.60		0.100
L	2.40		0.090	

**REEL SPECIFICATION**

P/N	PKG	QTY
SS22B THRU SS210B	SMB	3000

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